

an adhesive layer, provided on said at least one layer of the base coating layer and the intermediate layer; and

a conductive layer formed on at least one of the rear surface of the substrate and the front surface of the adhesive layer,

said method comprising forming said conductive layer on at least one of the rear surface of the substrate and the front surface of the adhesive layer by deposition.

2. (Amended) The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the conductive layer comprises at least one of Al, Cu, Ag, Ni, Ti, Fe, Cr, Zr, Ta, Zn, and an alloy containing at least one of Al, Cu, Ag, Ni, Ti, Fe, Cr, Zr, Ta and Zn.

3. (Amended) The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the conductive layer has a thickness of 1×10^{-4} to 0.02 μm .

4. (Amended) The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the adhesive layer comprises 100 parts by weight of a base polymer and 2 to 100 parts by weight of a tackifier resin, and the adhesive layer has a thickness of 2 to 90 μm .

5. (Amended) The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the base coating layer comprises at least one of a urethane adhesive and an electrostatic induction preventing adhesive.

6. (Amended) The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the intermediate layer comprises a polyolefin based resin.

7. (Amended) The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein both surfaces of the cover tape have a surface resistivity of 10^2 to $10^{13} \Omega/\square$.

8. (Amended) The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the cover tape has a light transmittance of 60% or more.

9. (Amended) The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the cover tape has a frictional electrification voltage of 3,000 V or less at the adhesive layer side surface.

10. (Amended) The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the substrate has a melting point of 90°C or more.

11. (Amended) A method for producing an electric-part-conveying member, said electric-part-conveying member comprising:

an electronic-part-storage member for storing an electronic part; and

a cover tape covering the electronic-part-storage member,

wherein the cover tape comprises at least four laminated layers of:

a substrate;

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substrate;

at least one layer of a base coating layer and an intermediate layer, provided on the

an adhesive layer, provided on said at least one layer of the base coating layer and the

intermediate layer; and

a conductive layer formed on at least one of the rear surface of the substrate and the front surface of the adhesive layer by deposition,

said method comprising forming said conductive layer on at least one side of the rear surface of the substrate and the front surface of the adhesive layer by deposition.

Please add the following new claims:

12. (New) The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the conductive layer has a thickness of from 1×10^{-4} to 0.007 μm .

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13. (New) The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the deposition is by vacuum deposition.

Amendment Under 37 C.F.R. § 1.111
U.S. Appln. No. 09/892,859

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APR 2004

14. (New) A cover tape for the electronic-part conveyance made by the method of claim

15. (New) An electric-part-conveying member made by the method of claim 11.